



- 10/100 Base-T for LAN and other Ethernet Applications
- Designed to meet IEEE802.3
- RJ45 jack cavity conforms to FCC rules and regulations Part 68, SUB Part F
- Industrial Temp: -40°C to +85°C

Electrical Specifications @ 25°C

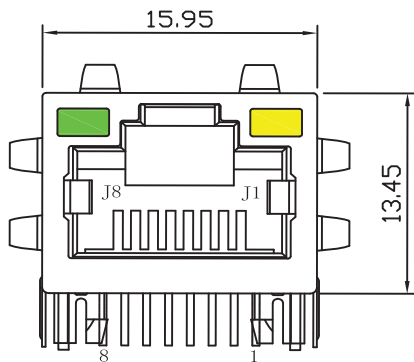
Part Number	OCL(uH Min) @ 100kHz	Turns Ratio (± 3%) TX/RX	Cross Talk (dB Min)			HI-POT (Test) (Vrms Min)
	With 0.1V 8mA DC Bias		1-30MHz	30-60MHz	60-100MHz	
AR11-4283I	350	1CT:1CT	-40	-35	-30	1500

Electrical Specifications @ 25°C

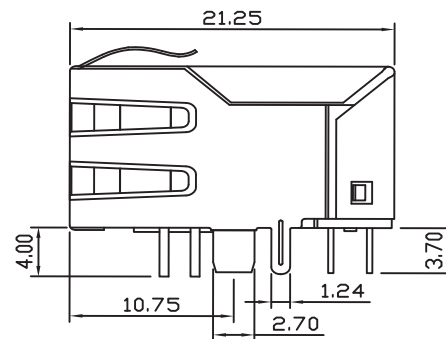
Part Number	Insertion Loss (dB Max)	Return Loss (dB Min)			CMR (dB Min)	
	1-100MHz	1-30MHz	30-60MHz	60-100MHz	1-50MHz	50-150MHz
AR11-4283I	-1.0	-18	-15	-12	-30	-20

All specifications subject to change without notice.

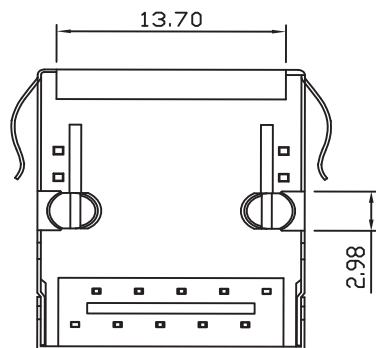
MECHANICAL



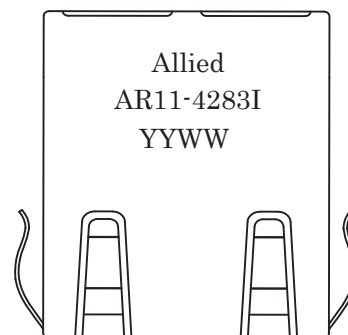
Front Side View



Left Side View



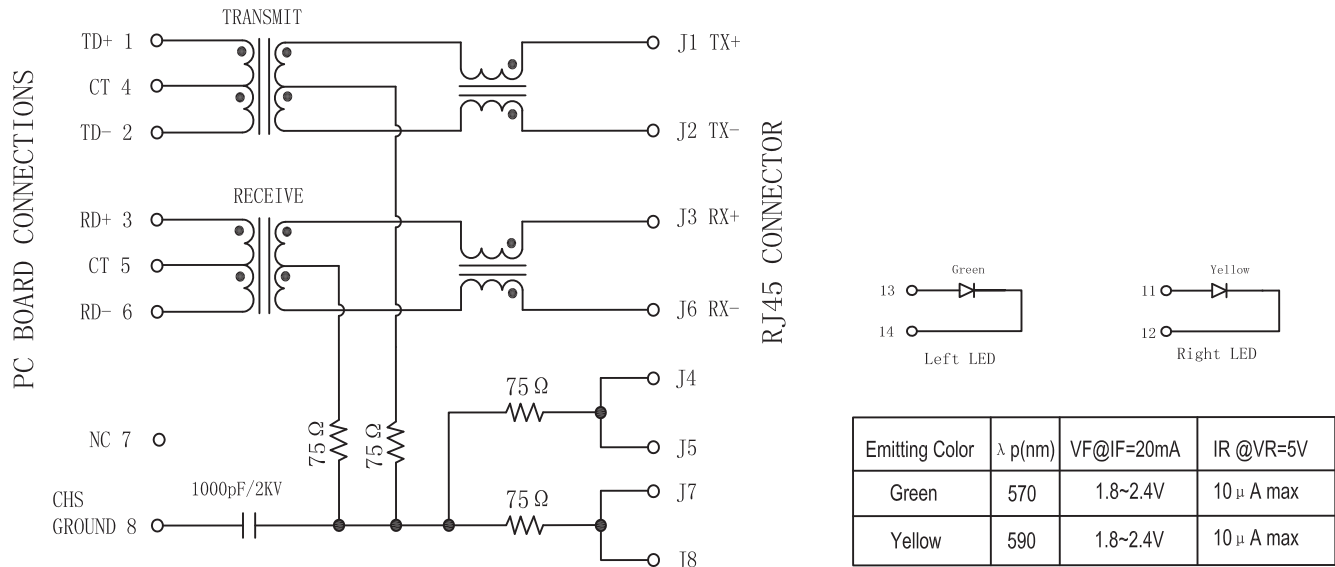
Bottom Side View



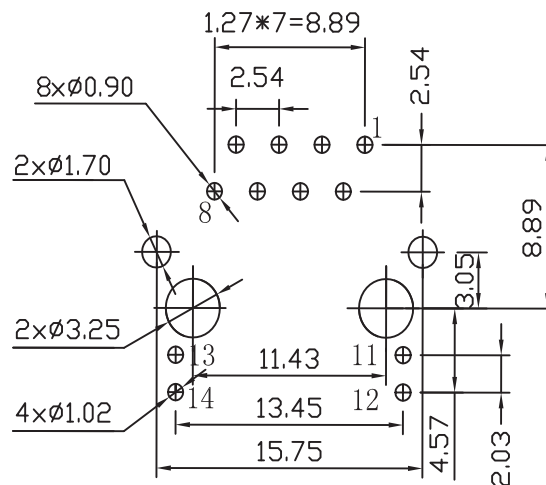
Top Side View



SCHEMATICS



PCB LAYOUT

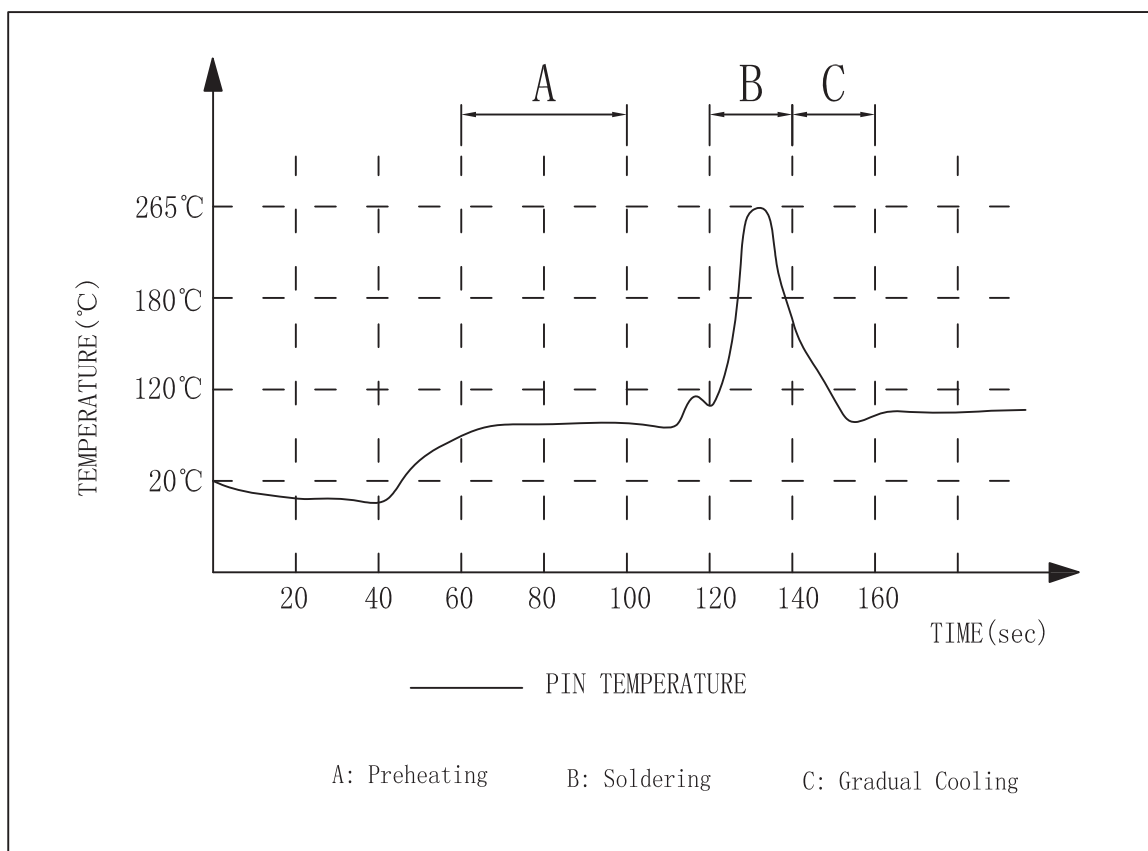


NOTES

1. Meets IEEE 802.3 specification
2. Connector Materials:
 Housing Material: Thermoplastic PBT+30%G. F UL94V-0
 Contact Material: Phosphor Bronze C5210R-EH Thickness=0.35mm
 Pins: Brass C2680R-H Thickness=0.35mm
 Shield: SUS 201-1/2H Thickness=0.2mm
 Contact plating: Gold 6 micro-inches min. In contact area.
3. Wave solder tip temperature: 265°C Max, 5 Sec Max



SUGGESTED PROFILE OF WAVE SOLDER FOR ROHS PRODUCT



(1) Tip Temperature: 265°C max

(2) Tip Temperature time: 5sec max

Note: The melting point of Tin: 219°C